

Features

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Green Device Available

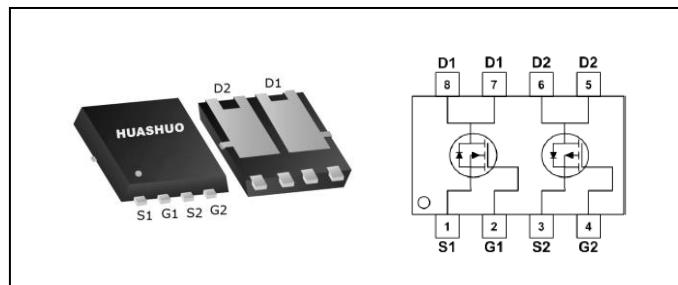
Product Summary

BVDSS	RDSON	ID
60V	38mΩ	5.5A
-60V	75mΩ	-4A

Applications

- Synchronous Rectification
- Motor Control.
- High Current,High Speed Switching
- Portable equipment application.

PRPAK3*3 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
V _{DS}	Drain-Source Voltage	60	-60	V
V _{GS}	Gate-Source Voltage	±20	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	5.5	-4	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	4	-3.2	A
I _{DM}	Pulsed Drain Current ²	20	-14	A
EAS	Single Pulse Avalanche Energy ³	22	29	mJ
I _{AS}	Avalanche Current	21	-24	A
P _D @T _A =25°C	Total Power Dissipation ⁴	2	2	W
T _{STG}	Storage Temperature Range	-55 to 150	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	85	°C/W

N-Ch and P-Ch Fast Switching MOSFETs
N-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	60	---	---	V
$\text{R}_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=5\text{A}$	---	38	50	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=4\text{A}$	---	45	70	
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}, \text{I}_D=250\mu\text{A}$	1.0	---	2.5	V
$\Delta \text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-4.56	---	$\text{mV}/^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=48\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=25^{\circ}\text{C}$	---	---	1	uA
		$\text{V}_{\text{DS}}=48\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=4\text{A}$	---	28	---	S
Q_{g}	Total Gate Charge (4.5V)	$\text{V}_{\text{DS}}=48\text{V}, \text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=4\text{A}$	---	19	---	nC
Q_{gs}	Gate-Source Charge		---	2.5	---	
Q_{gd}	Gate-Drain Charge		---	4.1	---	
$\text{T}_{\text{d}(\text{on})}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=30\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{R}_G=3.3\Omega$	---	3	---	ns
T_r	Rise Time		---	34	---	
$\text{T}_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	22	---	
T_f	Fall Time		---	6	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{f}=1\text{MHz}$	---	1031	---	pF
C_{oss}	Output Capacitance		---	66	---	
C_{rss}	Reverse Transfer Capacitance		---	46	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	2.5	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=1\text{A}, \text{T}_J=25^{\circ}\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $\text{V}_{\text{DD}}=25\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{L}=0.1\text{mH}, \text{I}_{\text{AS}}=21\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=-250\mu\text{A}$	-60	---	---	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=-10\text{V}$, $I_D=-3\text{A}$	---	75	100	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_D=-3\text{A}$	---	90	120	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D = -250\mu\text{A}$	-1.0	---	-2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	4.32	---	$\text{mV}/^{\circ}\text{C}$
$I_{\text{DS}(\text{SS})}$	Drain-Source Leakage Current	$V_{\text{DS}}=-48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^{\circ}\text{C}$	---	---	1	uA
		$V_{\text{DS}}=-48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$, $I_D=-3\text{A}$	---	15	---	S
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	13.5	---	Ω
Q_g	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-48\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_D=-3\text{A}$	---	9.7	---	nC
Q_{gs}	Gate-Source Charge		---	3.1	---	
Q_{gd}	Gate-Drain Charge		---	2.9	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=-15\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_g=3.3\Omega$, $I_D=-1\text{A}$	---	29	---	ns
T_r	Rise Time		---	20	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	61	---	
T_f	Fall Time		---	7	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1444	---	pF
C_{oss}	Output Capacitance		---	98	---	
C_{rss}	Reverse Transfer Capacitance		---	70	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	-2.5	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25^{\circ}\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=-25\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=-24\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



N-Ch and P-Ch Fast Switching MOSFETs

N-Channel Typical Characteristics

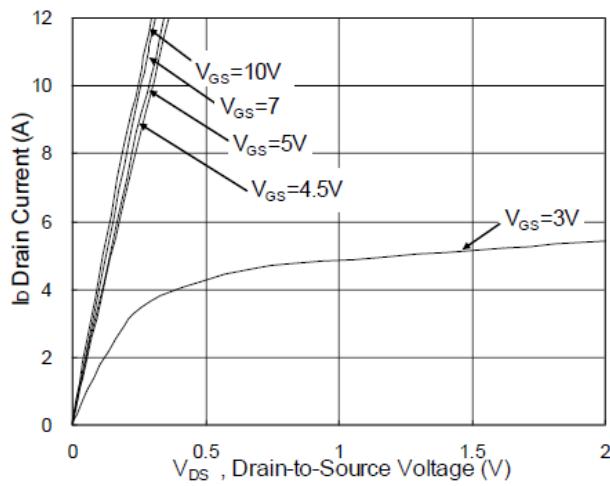


Fig.1 Typical Output Characteristics

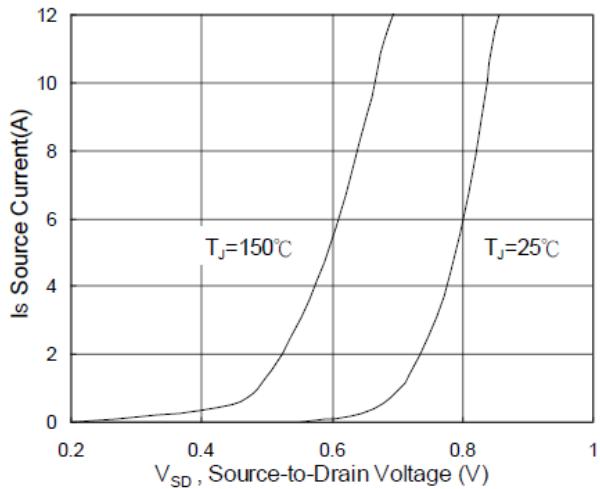


Fig.3 Forward Characteristics of Reverse

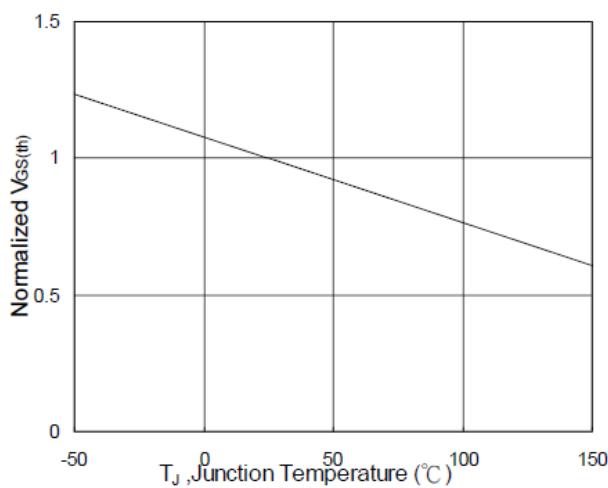


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

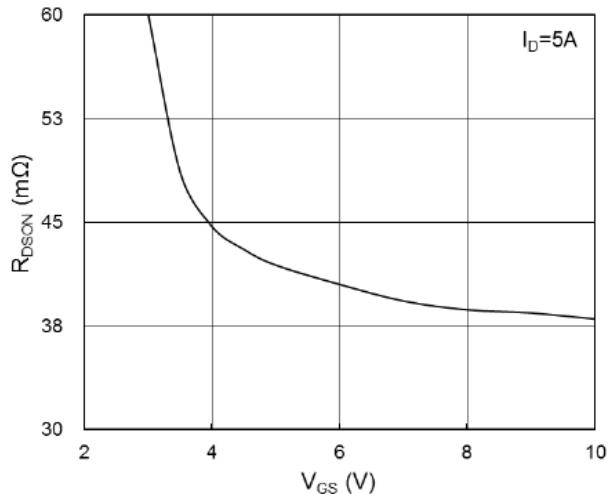


Fig.2 On-Resistance vs. G-S Voltage

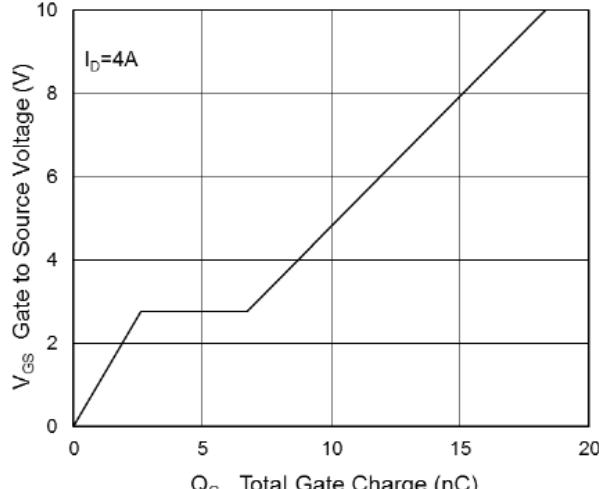


Fig.4 Gate-Charge Characteristics

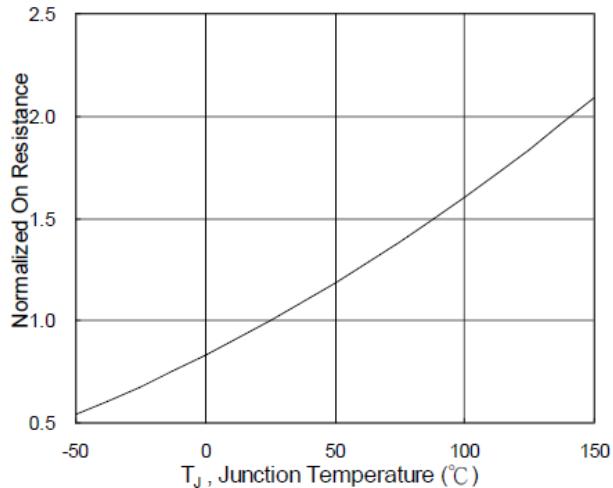


Fig.6 Normalized R_{DSon} vs. T_J



N-Ch and P-Ch Fast Switching MOSFETs

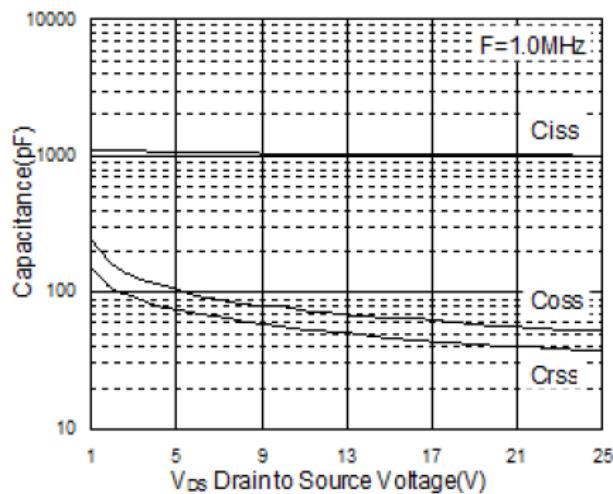


Fig.7 Capacitance

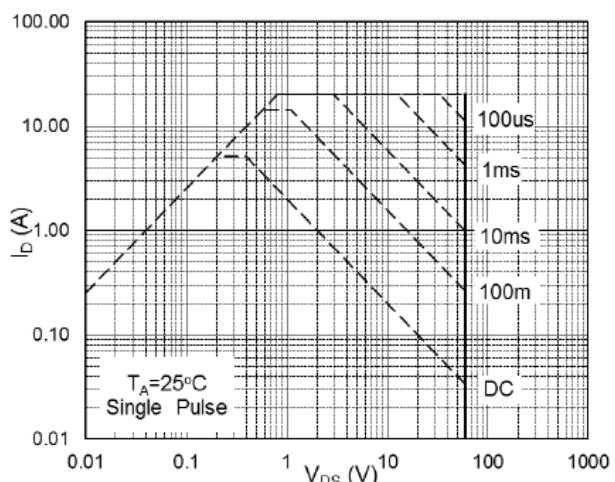


Fig.8 Safe Operating Area

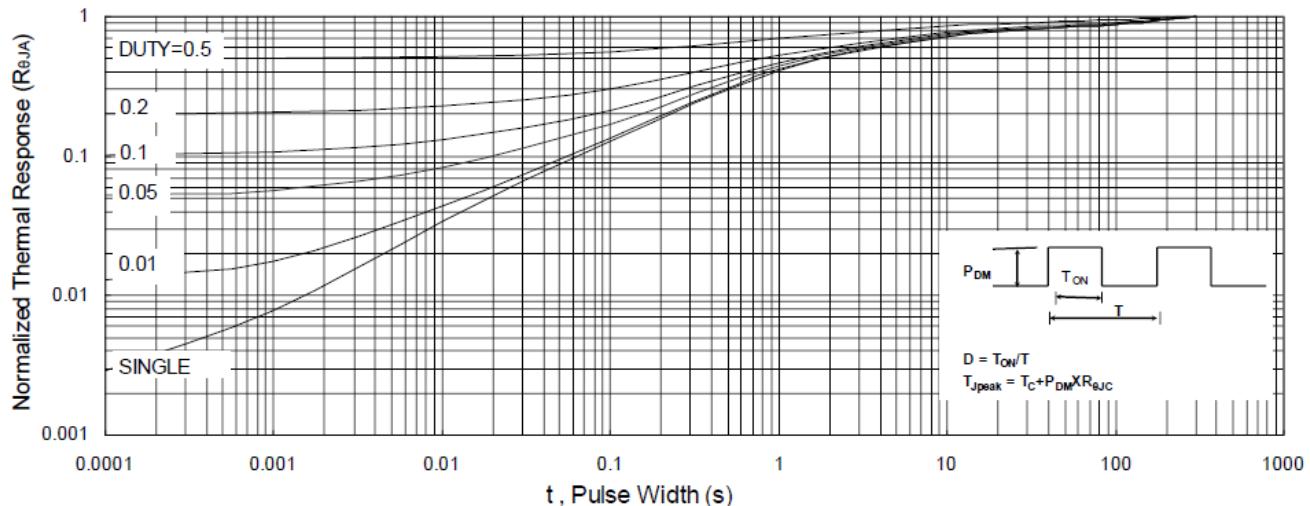


Fig.9 Normalized Maximum Transient Thermal Impedance

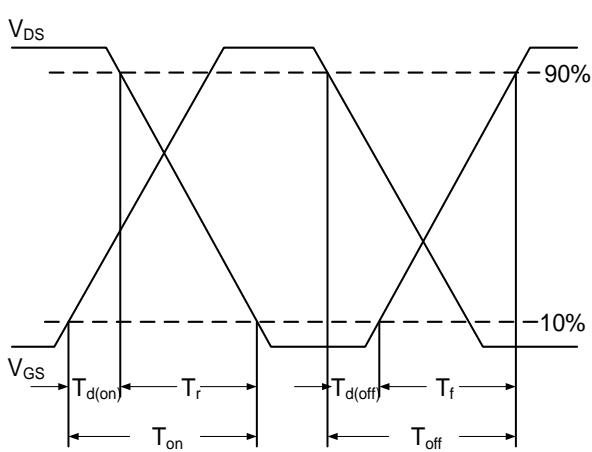


Fig.10 Switching Time Waveform

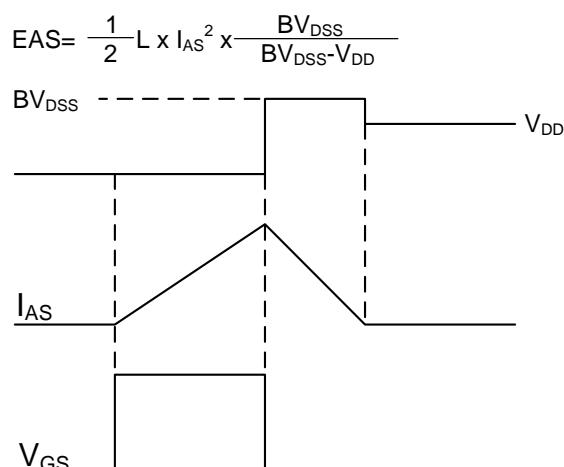


Fig.11 Unclamped Inductive Switching Wave



N-Ch and P-Ch Fast Switching MOSFETs

P-Channel Typical Characteristics

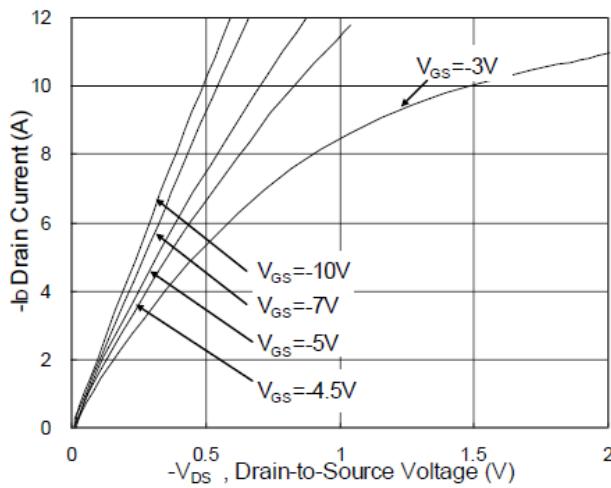


Fig.1 Typical Output Characteristics

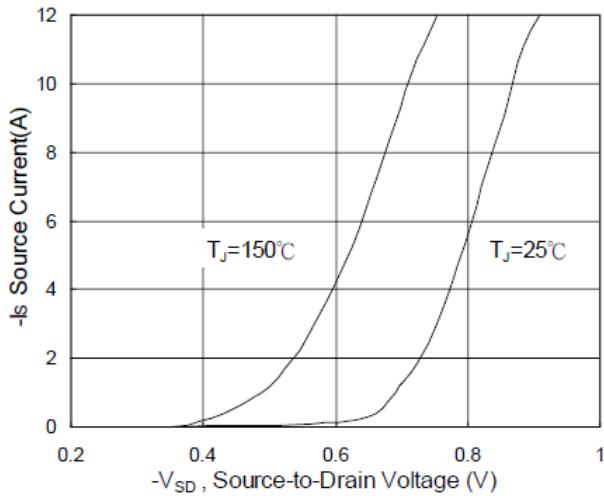


Fig.3 Forward Characteristics of Reverse

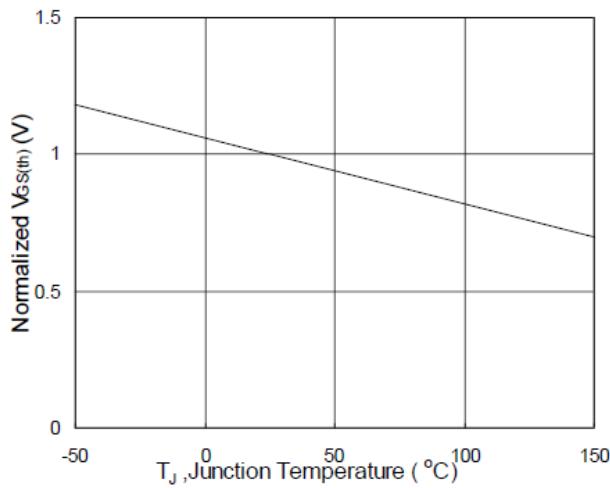


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

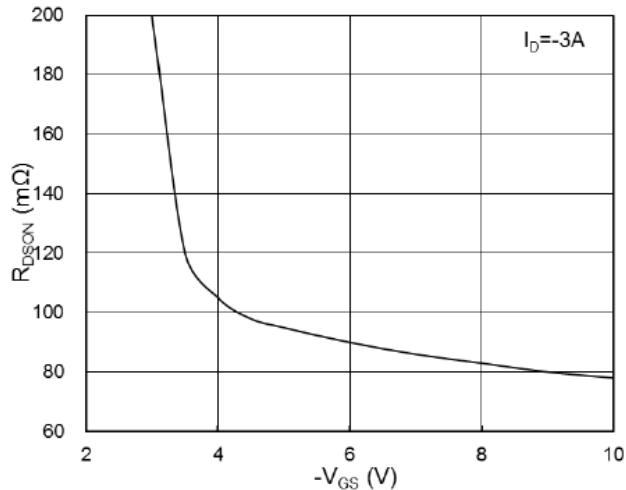


Fig.2 On-Resistance v.s Gate-Source

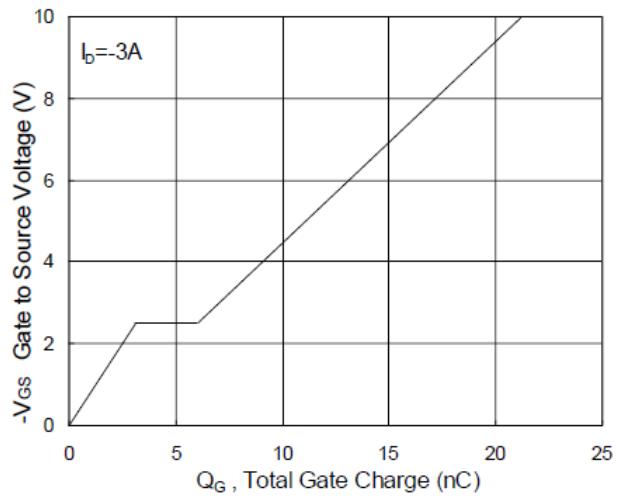


Fig.4 Gate-Charge Characteristics

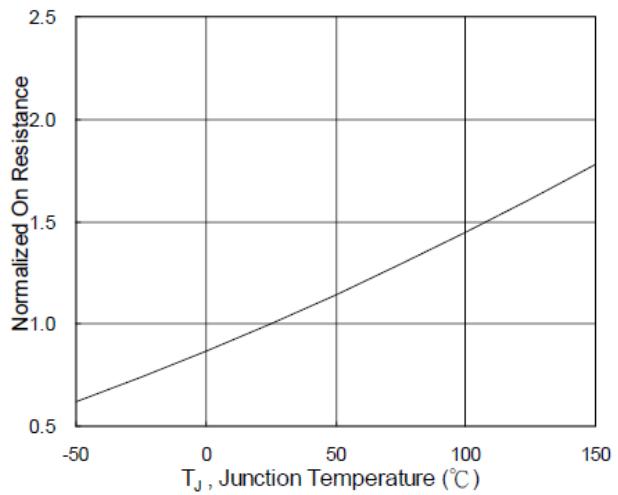


Fig.6 Normalized $R_{DS(on)}$ v.s T_J



N-Ch and P-Ch Fast Switching MOSFETs

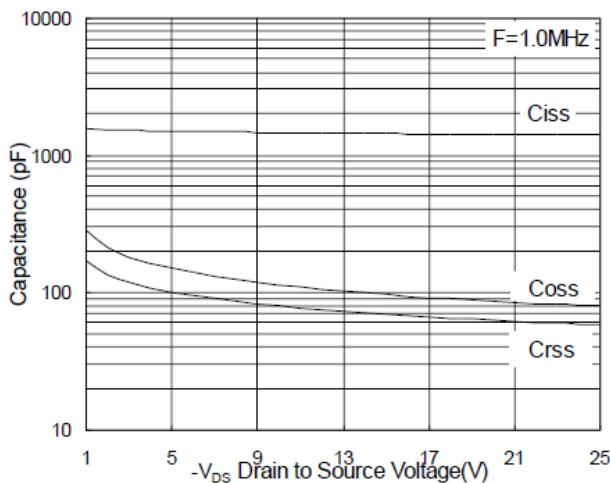


Fig.7 Capacitance

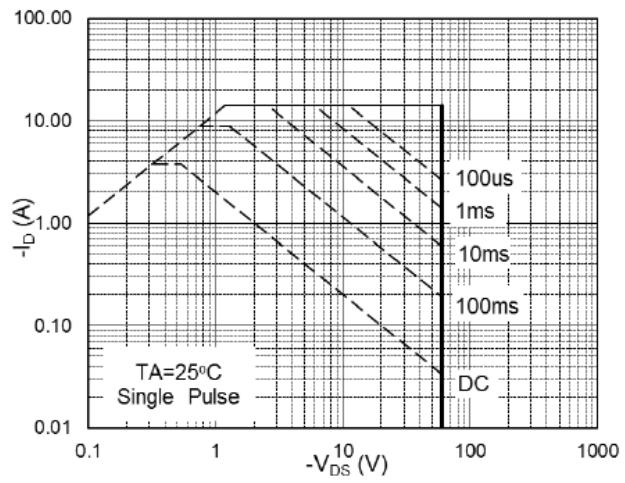


Fig.8 Safe Operating Area

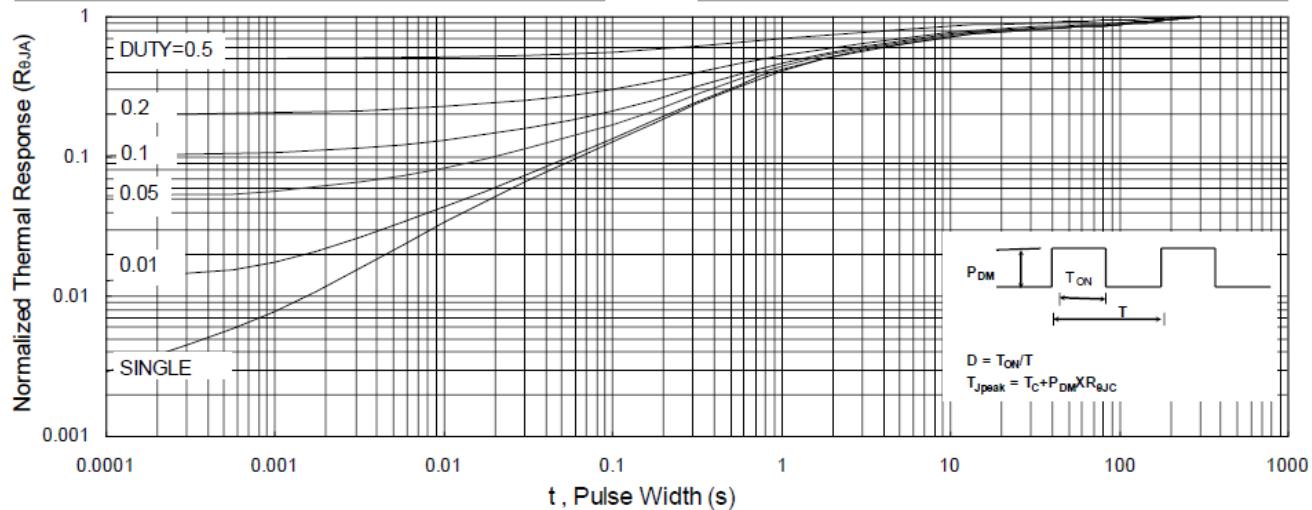


Fig.9 Normalized Maximum Transient Thermal Impedance

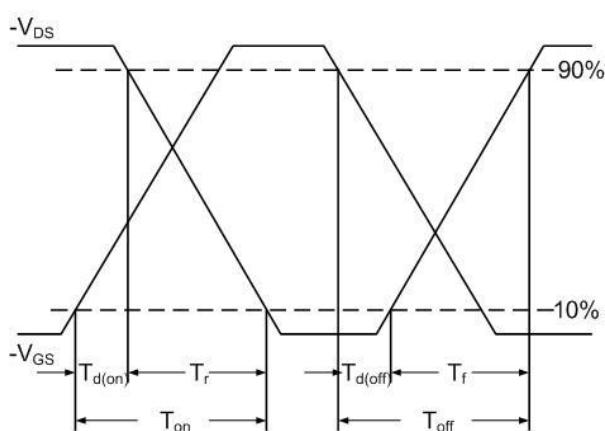


Fig.10 Switching Time Waveform

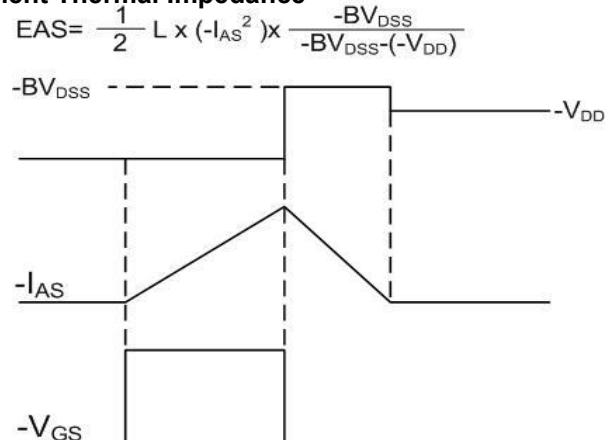


Fig.11 Unclamped Inductive Waveform